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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Active
Number of LABs/CLBs	162000
Number of Logic Elements/Cells	2835000
Total RAM Bits	396150400
Number of I/O	572
Number of Gates	-
Voltage - Supply	0.825V ~ 0.876V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 100°C (TJ)
Package / Case	2104-BBGA, FCBGA
Supplier Device Package	2104-FCBGA (47.5x47.5)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/xilinx/xcvu11p-2flgb2104e">https://www.e-xfl.com/product-detail/xilinx/xcvu11p-2flgb2104e</a>

# Summary of Features

## Processing System Overview

UltraScale+ MPSoCs feature dual and quad core variants of the ARM Cortex-A53 (APU) with dual-core ARM Cortex-R5 (RPU) processing system (PS). Some devices also include a dedicated ARM Mali™-400 MP2 graphics processing unit (GPU). See [Table 2](#).

*Table 2: Zynq UltraScale+ MPSoC Device Features*

	CG Devices	EG Devices	EV Devices
APU	Dual-core ARM Cortex-A53	Quad-core ARM Cortex-A53	Quad-core ARM Cortex-A53
RPU	Dual-core ARM Cortex-R5	Dual-core ARM Cortex-R5	Dual-core ARM Cortex-R5
GPU	–	Mali-400MP2	Mali-400MP2
VCU	–	–	H.264/H.265

To support the processors' functionality, a number of peripherals with dedicated functions are included in the PS. For interfacing to external memories for data or configuration storage, the PS includes a multi-protocol dynamic memory controller, a DMA controller, a NAND controller, an SD/eMMC controller and a Quad SPI controller. In addition to interfacing to external memories, the APU also includes a Level-1 (L1) and Level-2 (L2) cache hierarchy; the RPU includes an L1 cache and Tightly Coupled memory subsystem. Each has access to a 256KB on-chip memory.

For high-speed interfacing, the PS includes 4 channels of transmit (TX) and receive (RX) pairs of transceivers, called PS-GTR transceivers, supporting data rates of up to 6.0Gb/s. These transceivers can interface to the high-speed peripheral blocks to support PCIe Gen2 root complex or end point in x1, x2, or x4 configurations; Serial-ATA (SATA) at 1.5Gb/s, 3.0Gb/s, or 6.0Gb/s data rates; and up to two lanes of Display Port at 1.62Gb/s, 2.7Gb/s, or 5.4Gb/s data rates. The PS-GTR transceivers can also interface to components over USB 3.0 and Serial Gigabit Media Independent Interface (SGMII).

For general connectivity, the PS includes: a pair of USB 2.0 controllers, which can be configured as host, device, or On-The-Go (OTG); an I2C controller; a UART; and a CAN2.0B controller that conforms to ISO11898-1. There are also four triple speed Ethernet MACs and 128 bits of GPIO, of which 78 bits are available through the MIO and 96 through the EMIO.

High-bandwidth connectivity based on the ARM AMBA® AXI4 protocol connects the processing units with the peripherals and provides interface between the PS and the programmable logic (PL).

For additional information, go to: [DS891](#), *Zynq UltraScale+ MPSoC Overview*.

## I/O, Transceiver, PCIe, 100G Ethernet, and 150G Interlaken

Data is transported on and off chip through a combination of the high-performance parallel SelectIO™ interface and high-speed serial transceiver connectivity. I/O blocks provide support for cutting-edge memory interface and network protocols through flexible I/O standard and voltage support. The serial transceivers in the UltraScale architecture-based devices transfer data up to 32.75Gb/s, enabling 25G+ backplane designs with dramatically lower power per bit than previous generation transceivers. All transceivers, except the PS-GTR, support the required data rates for PCIe Gen3, and Gen4 (rev 0.5), and integrated blocks for PCIe enable UltraScale devices to support up to Gen4 x8 and Gen3 x16 Endpoint and Root Port designs. Integrated blocks for 150Gb/s Interlaken and 100Gb/s Ethernet (100G MAC/PCS) extend the capabilities of UltraScale devices, enabling simple, reliable support for Nx100G switch and bridge applications. Virtex UltraScale+ HBM devices include Cache Coherent Interconnect for Accelerators (CCIX) ports for coherently sharing data with different processors.

## Clocks and Memory Interfaces

UltraScale devices contain powerful clock management circuitry, including clock synthesis, buffering, and routing components that together provide a highly capable framework to meet design requirements. The clock network allows for extremely flexible distribution of clocks to minimize the skew, power consumption, and delay associated with clock signals. The clock management technology is tightly integrated with dedicated memory interface circuitry to enable support for high-performance external memories, including DDR4. In addition to parallel memory interfaces, UltraScale devices support serial memories, such as hybrid memory cube (HMC).

## Routing, SSI, Logic, Storage, and Signal Processing

Configurable Logic Blocks (CLBs) containing 6-input look-up tables (LUTs) and flip-flops, DSP slices with 27x18 multipliers, 36Kb block RAMs with built-in FIFO and ECC support, and 4Kx72 UltraRAM blocks (in UltraScale+ devices) are all connected with an abundance of high-performance, low-latency interconnect. In addition to logical functions, the CLB provides shift register, multiplexer, and carry logic functionality as well as the ability to configure the LUTs as distributed memory to complement the highly capable and configurable block RAMs. The DSP slice, with its 96-bit-wide XOR functionality, 27-bit pre-adder, and 30-bit A input, performs numerous independent functions including multiply accumulate, multiply add, and pattern detect. In addition to the device interconnect, in devices using SSI technology, signals can cross between super-logic regions (SLRs) using dedicated, low-latency interface tiles. These combined routing resources enable easy support for next-generation bus data widths. Virtex UltraScale+ HBM devices include up to 8GB of high bandwidth memory.

## Configuration, Encryption, and System Monitoring

The configuration and encryption block performs numerous device-level functions critical to the successful operation of the FPGA or MPSoC. This high-performance configuration block enables device configuration from external media through various protocols, including PCIe, often with no requirement to use multi-function I/O pins during configuration. The configuration block also provides 256-bit AES-GCM decryption capability at the same performance as unencrypted configuration. Additional features include SEU detection and correction, partial reconfiguration support, and battery-backed RAM or eFUSE technology for AES key storage to provide additional security. The System Monitor enables the monitoring of the physical environment via on-chip temperature and supply sensors and can also monitor up to 17 external analog inputs. With UltraScale+ MPSoCs, the device is booted via the Configuration and Security Unit (CSU), which supports secure boot via the 256-bit AES-GCM and SHA/384 blocks. The cryptographic engines in the CSU can be used in the MPSoC after boot for user encryption.

## Migrating Devices

UltraScale and UltraScale+ families provide footprint compatibility to enable users to migrate designs from one device or family to another. Any two packages with the same footprint identifier code are footprint compatible. For example, Kintex UltraScale devices in the A1156 packages are footprint compatible with Kintex UltraScale+ devices in the A1156 packages. Likewise, Virtex UltraScale devices in the B2104 packages are compatible with Virtex UltraScale+ devices and Kintex UltraScale devices in the B2104 packages. All valid device/package combinations are provided in the Device-Package Combinations and Maximum I/Os tables in this document. Refer to [UG583](#), *UltraScale Architecture PCB Design User Guide* for more detail on migrating between UltraScale and UltraScale+ devices and packages.

# Kintex UltraScale+ FPGA Feature Summary

Table 5: Kintex UltraScale+ FPGA Feature Summary

	KU3P	KU5P	KU9P	KU11P	KU13P	KU15P
System Logic Cells	355,950	474,600	599,550	653,100	746,550	1,143,450
CLB Flip-Flops	325,440	433,920	548,160	597,120	682,560	1,045,440
CLB LUTs	162,720	216,960	274,080	298,560	341,280	522,720
Max. Distributed RAM (Mb)	4.7	6.1	8.8	9.1	11.3	9.8
Block RAM Blocks	360	480	912	600	744	984
Block RAM (Mb)	12.7	16.9	32.1	21.1	26.2	34.6
UltraRAM Blocks	48	64	0	80	112	128
UltraRAM (Mb)	13.5	18.0	0	22.5	31.5	36.0
CMTs (1 MMCM and 2 PLLs)	4	4	4	8	4	11
Max. HP I/O <sup>(1)</sup>	208	208	208	416	208	572
Max. HD I/O <sup>(2)</sup>	96	96	96	96	96	96
DSP Slices	1,368	1,824	2,520	2,928	3,528	1,968
System Monitor	1	1	1	1	1	1
GTH Transceiver 16.3Gb/s	0	0	28	32	28	44
GTY Transceivers 32.75Gb/s <sup>(3)</sup>	16	16	0	20	0	32
Transceiver Fractional PLLs	8	8	14	26	14	38
PCIe Gen3 x16 and Gen4 x8	1	1	0	4	0	5
150G Interlaken	0	0	0	1	0	4
100G Ethernet w/RS-FEC	0	1	0	2	0	4

## Notes:

1. HP = High-performance I/O with support for I/O voltage from 1.0V to 1.8V.
2. HD = High-density I/O with support for I/O voltage from 1.2V to 3.3V.
3. GTY transceiver line rates are package limited: SFVB784 to 12.5Gb/s; FFVA676, FFVD900, and FFVA1156 to 16.3Gb/s. See [Table 6](#).

# Virtex UltraScale+ FPGA Feature Summary

Table 9: Virtex UltraScale+ FPGA Feature Summary

	VU3P	VU5P	VU7P	VU9P	VU11P	VU13P	VU31P	VU33P	VU35P	VU37P
System Logic Cells	862,050	1,313,763	1,724,100	2,586,150	2,835,000	3,780,000	961,800	961,800	1,906,800	2,851,800
CLB Flip-Flops	788,160	1,201,154	1,576,320	2,364,480	2,592,000	3,456,000	879,360	879,360	1,743,360	2,607,360
CLB LUTs	394,080	600,577	788,160	1,182,240	1,296,000	1,728,000	439,680	439,680	871,680	1,303,680
Max. Distributed RAM (Mb)	12.0	18.3	24.1	36.1	36.2	48.3	12.5	12.5	24.6	36.7
Block RAM Blocks	720	1,024	1,440	2,160	2,016	2,688	672	672	1,344	2,016
Block RAM (Mb)	25.3	36.0	50.6	75.9	70.9	94.5	23.6	23.6	47.3	70.9
UltraRAM Blocks	320	470	640	960	960	1,280	320	320	640	960
UltraRAM (Mb)	90.0	132.2	180.0	270.0	270.0	360.0	90.0	90.0	180.0	270.0
HBM DRAM (GB)	–	–	–	–	–	–	4	8	8	8
CMTs (1 MMCM and 2 PLLs)	10	20	20	30	12	16	4	4	8	12
Max. HP I/O <sup>(1)</sup>	520	832	832	832	624	832	208	208	416	624
DSP Slices	2,280	3,474	4,560	6,840	9,216	12,288	2,880	2,880	5,952	9,024
System Monitor	1	2	2	3	3	4	1	1	2	3
GTY Transceivers 32.75Gb/s <sup>(2)</sup>	40	80	80	120	96	128	32	32	64	96
Transceiver Fractional PLLs	20	40	40	60	48	64	16	16	32	48
PCIe Gen3 x16 and Gen4 x8	2	4	4	6	3	4	4	4	5	6
CCIX Ports <sup>(3)</sup>	–	–	–	–	–	–	4	4	4	4
150G Interlaken	3	4	6	9	6	8	0	0	2	4
100G Ethernet w/RS-FEC	3	4	6	9	9	12	2	2	5	8

## Notes:

1. HP = High-performance I/O with support for I/O voltage from 1.0V to 1.8V.
2. GTY transceivers in the FLGF1924 package support data rates up to 16.3Gb/s. See [Table 10](#).
3. A CCIX port requires the use of a PCIe Gen3 x16 / Gen4 x8 block.

# Zynq UltraScale+: CG Device Feature Summary

Table 11: Zynq UltraScale+: CG Device Feature Summary

	ZU2CG	ZU3CG	ZU4CG	ZU5CG	ZU6CG	ZU7CG	ZU9CG
Application Processing Unit	Dual-core ARM Cortex-A53 MPCore with CoreSight; NEON & Single/Double Precision Floating Point; 32KB/32KB L1 Cache, 1MB L2 Cache						
Real-Time Processing Unit	Dual-core ARM Cortex-R5 with CoreSight; Single/Double Precision Floating Point; 32KB/32KB L1 Cache, and TCM						
Embedded and External Memory	256KB On-Chip Memory w/ECC; External DDR4; DDR3; DDR3L; LPDDR4; LPDDR3; External Quad-SPI; NAND; eMMC						
General Connectivity	214 PS I/O; UART; CAN; USB 2.0; I2C; SPI; 32b GPIO; Real Time Clock; WatchDog Timers; Triple Timer Counters						
High-Speed Connectivity	4 PS-GTR; PCIe Gen1/2; Serial ATA 3.1; DisplayPort 1.2a; USB 3.0; SGMII						
System Logic Cells	103,320	154,350	192,150	256,200	469,446	504,000	599,550
CLB Flip-Flops	94,464	141,120	175,680	234,240	429,208	460,800	548,160
CLB LUTs	47,232	70,560	87,840	117,120	214,604	230,400	274,080
Distributed RAM (Mb)	1.2	1.8	2.6	3.5	6.9	6.2	8.8
Block RAM Blocks	150	216	128	144	714	312	912
Block RAM (Mb)	5.3	7.6	4.5	5.1	25.1	11.0	32.1
UltraRAM Blocks	0	0	48	64	0	96	0
UltraRAM (Mb)	0	0	14.0	18.0	0	27.0	0
DSP Slices	240	360	728	1,248	1,973	1,728	2,520
CMTs	3	3	4	4	4	8	4
Max. HP I/O <sup>(1)</sup>	156	156	156	156	208	416	208
Max. HD I/O <sup>(2)</sup>	96	96	96	96	120	48	120
System Monitor	2	2	2	2	2	2	2
GTH Transceiver 16.3Gb/s <sup>(3)</sup>	0	0	16	16	24	24	24
GTY Transceivers 32.75Gb/s	0	0	0	0	0	0	0
Transceiver Fractional PLLs	0	0	8	8	12	12	12
PCIe Gen3 x16 and Gen4 x8	0	0	2	2	0	2	0
150G Interlaken	0	0	0	0	0	0	0
100G Ethernet w/ RS-FEC	0	0	0	0	0	0	0

## Notes:

1. HP = High-performance I/O with support for I/O voltage from 1.0V to 1.8V.
2. HD = High-density I/O with support for I/O voltage from 1.2V to 3.3V.
3. GTH transceivers in the SFVC784 package support data rates up to 12.5Gb/s. See [Table 12](#).

# Zynq UltraScale+: EG Device Feature Summary

Table 13: Zynq UltraScale+: EG Device Feature Summary

	ZU2EG	ZU3EG	ZU4EG	ZU5EG	ZU6EG	ZU7EG	ZU9EG	ZU11EG	ZU15EG	ZU17EG	ZU19EG
Application Processing Unit	Quad-core ARM Cortex-A53 MPCore with CoreSight; NEON & Single/Double Precision Floating Point; 32KB/32KB L1 Cache, 1MB L2 Cache										
Real-Time Processing Unit	Dual-core ARM Cortex-R5 with CoreSight; Single/Double Precision Floating Point; 32KB/32KB L1 Cache, and TCM										
Embedded and External Memory	256KB On-Chip Memory w/ECC; External DDR4; DDR3; DDR3L; LPDDR4; LPDDR3; External Quad-SPI; NAND; eMMC										
General Connectivity	214 PS I/O; UART; CAN; USB 2.0; I2C; SPI; 32b GPIO; Real Time Clock; WatchDog Timers; Triple Timer Counters										
High-Speed Connectivity	4 PS-GTR; PCIe Gen1/2; Serial ATA 3.1; DisplayPort 1.2a; USB 3.0; SGMII										
Graphic Processing Unit	ARM Mali-400 MP2; 64KB L2 Cache										
System Logic Cells	103,320	154,350	192,150	256,200	469,446	504,000	599,550	653,100	746,550	926,194	1,143,450
CLB Flip-Flops	94,464	141,120	175,680	234,240	429,208	460,800	548,160	597,120	682,560	846,806	1,045,440
CLB LUTs	47,232	70,560	87,840	117,120	214,604	230,400	274,080	298,560	341,280	423,403	522,720
Distributed RAM (Mb)	1.2	1.8	2.6	3.5	6.9	6.2	8.8	9.1	11.3	8.0	9.8
Block RAM Blocks	150	216	128	144	714	312	912	600	744	796	984
Block RAM (Mb)	5.3	7.6	4.5	5.1	25.1	11.0	32.1	21.1	26.2	28.0	34.6
UltraRAM Blocks	0	0	48	64	0	96	0	80	112	102	128
UltraRAM (Mb)	0	0	14.0	18.0	0	27.0	0	22.5	31.5	28.7	36.0
DSP Slices	240	360	728	1,248	1,973	1,728	2,520	2,928	3,528	1,590	1,968
CMTs	3	3	4	4	4	8	4	8	4	11	11
Max. HP I/O <sup>(1)</sup>	156	156	156	156	208	416	208	416	208	572	572
Max. HD I/O <sup>(2)</sup>	96	96	96	96	120	48	120	96	120	96	96
System Monitor	2	2	2	2	2	2	2	2	2	2	2
GTH Transceiver 16.3Gb/s <sup>(3)</sup>	0	0	16	16	24	24	24	32	24	44	44
GTY Transceivers 32.75Gb/s	0	0	0	0	0	0	0	16	0	28	28
Transceiver Fractional PLLs	0	0	8	8	12	12	12	24	12	36	36
PCIe Gen3 x16 and Gen4 x8	0	0	2	2	0	2	0	4	0	4	5
150G Interlaken	0	0	0	0	0	0	0	1	0	2	4
100G Ethernet w/ RS-FEC	0	0	0	0	0	0	0	2	0	2	4

## Notes:

1. HP = High-performance I/O with support for I/O voltage from 1.0V to 1.8V.
2. HD = High-density I/O with support for I/O voltage from 1.2V to 3.3V.
3. GTH transceivers in the SFVC784 package support data rates up to 12.5Gb/s. See [Table 14](#).



# Zynq UltraScale+: EG Device-Package Combinations and Maximum I/Os

Table 14: Zynq UltraScale+: EG Device-Package Combinations and Maximum I/Os

Package (1)(2)(3)(4)(5)	Package Dimensions (mm)	ZU2EG	ZU3EG	ZU4EG	ZU5EG	ZU6EG	ZU7EG	ZU9EG	ZU11EG	ZU15EG	ZU17EG	ZU19EG
		HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY
SBVA484(6)	19x19	24, 58 0, 0	24, 58 0, 0									
SFVA625	21x21	24, 156 0, 0	24, 156 0, 0									
SFVC784(7)	23x23	96, 156 0, 0	96, 156 0, 0	96, 156 4, 0	96, 156 4, 0							
FBVB900	31x31			48, 156 16, 0	48, 156 16, 0		48, 156 16, 0					
FFVC900	31x31					48, 156 16, 0		48, 156 16, 0		48, 156 16, 0		
FFVB1156	35x35					120, 208 24, 0		120, 208 24, 0		120, 208 24, 0		
FFVC1156	35x35						48, 312 20, 0		48, 312 20, 0			
FFVB1517	40x40								72, 416 16, 0		72, 572 16, 0	72, 572 16, 0
FFVF1517	40x40						48, 416 24, 0		48, 416 32, 0			
FFVC1760	42.5x42.5								96, 416 32, 16		96, 416 32, 16	96, 416 32, 16
FFVD1760	42.5x42.5										48, 260 44, 28	48, 260 44, 28
FFVE1924	45x45										96, 572 44, 0	96, 572 44, 0

## Notes:

- Go to [Ordering Information](#) for package designation details.
- FB/FF packages have 1.0mm ball pitch. SB/SF packages have 0.8mm ball pitch.
- All device package combinations bond out 4 PS-GTR transceivers.
- All device package combinations bond out 214 PS I/O except ZU2EG and ZU3EG in the SBVA484 and SFVA625 packages, which bond out 170 PS I/Os.
- Packages with the same last letter and number sequence, e.g., A484, are footprint compatible with all other UltraScale architecture-based devices with the same sequence. The footprint compatible devices within this family are outlined.
- All 58 HP I/O pins are powered by the same V<sub>CCO</sub> supply.
- GTH transceivers in the SFVC784 package support data rates up to 12.5Gb/s.

# High-Speed Serial Transceivers

Serial data transmission between devices on the same PCB, over backplanes, and across even longer distances is becoming increasingly important for scaling to 100Gb/s and 400Gb/s line cards. Specialized dedicated on-chip circuitry and differential I/O capable of coping with the signal integrity issues are required at these high data rates.

Three types of transceivers are used in the UltraScale architecture: GTH and GTY in FPGAs and MPSoC PL, and PS-GTR in the MPSoC PS. All transceivers are arranged in groups of four, known as a transceiver Quad. Each serial transceiver is a combined transmitter and receiver. [Table 17](#) compares the available transceivers.

**Table 17: Transceiver Information**

	Kintex UltraScale		Kintex UltraScale+		Virtex UltraScale		Virtex UltraScale+	Zynq UltraScale+		
Type	GTH	GTY	GTH	GTY	GTH	GTY	GTY	PS-GTR	GTH	GTY
Qty	16–64	0–32	20–60	0–60	20–60	0–60	40–128	4	0–44	0–28
Max. Data Rate	16.3Gb/s	16.3Gb/s	16.3Gb/s	32.75Gb/s	16.3Gb/s	30.5Gb/s	32.75Gb/s	6.0Gb/s	16.3Gb/s	32.75Gb/s
Min. Data Rate	0.5Gb/s	0.5Gb/s	0.5Gb/s	0.5Gb/s	0.5Gb/s	0.5Gb/s	0.5Gb/s	1.25Gb/s	0.5Gb/s	0.5Gb/s
Key Apps	<ul style="list-style-type: none"> <li>Backplane</li> <li>PCIe Gen4</li> <li>HMC</li> </ul>	<ul style="list-style-type: none"> <li>Backplane</li> <li>PCIe Gen4</li> <li>HMC</li> </ul>	<ul style="list-style-type: none"> <li>Backplane</li> <li>PCIe Gen4</li> <li>HMC</li> </ul>	<ul style="list-style-type: none"> <li>100G+ Optics</li> <li>Chip-to-Chip</li> <li>25G+ Backplane</li> <li>HMC</li> </ul>	<ul style="list-style-type: none"> <li>Backplane</li> <li>PCIe Gen4</li> <li>HMC</li> </ul>	<ul style="list-style-type: none"> <li>100G+ Optics</li> <li>Chip-to-Chip</li> <li>25G+ Backplane</li> <li>HMC</li> </ul>	<ul style="list-style-type: none"> <li>100G+ Optics</li> <li>Chip-to-Chip</li> <li>25G+ Backplane</li> <li>HMC</li> </ul>	<ul style="list-style-type: none"> <li>PCIe Gen2</li> <li>USB</li> <li>Ethernet</li> </ul>	<ul style="list-style-type: none"> <li>Backplane</li> <li>PCIe Gen4</li> <li>HMC</li> </ul>	<ul style="list-style-type: none"> <li>100G+ Optics</li> <li>Chip-to-Chip</li> <li>25G+ Backplane</li> <li>HMC</li> </ul>

The following information in this section pertains to the GTH and GTY only.

The serial transmitter and receiver are independent circuits that use an advanced phase-locked loop (PLL) architecture to multiply the reference frequency input by certain programmable numbers between 4 and 25 to become the bit-serial data clock. Each transceiver has a large number of user-definable features and parameters. All of these can be defined during device configuration, and many can also be modified during operation.

## Integrated Interface Blocks for PCI Express Designs

The UltraScale architecture includes integrated blocks for PCIe technology that can be configured as an Endpoint or Root Port. UltraScale devices are compliant to the PCI Express Base Specification Revision 3.0. UltraScale+ devices are compliant to the PCI Express Base Specification Revision 3.1 for Gen3 and lower data rates, and compatible with the PCI Express Base Specification Revision 4.0 (rev 0.5) for Gen4 data rates.

The Root Port can be used to build the basis for a compatible Root Complex, to allow custom chip-to-chip communication via the PCI Express protocol, and to attach ASSP Endpoint devices, such as Ethernet Controllers or Fibre Channel HBAs, to the FPGA or MPSoC.

This block is highly configurable to system design requirements and can operate up to the maximum lane widths and data rates listed in [Table 18](#).

*Table 18: PCIe Maximum Configurations*

	Kintex UltraScale	Kintex UltraScale+	Virtex UltraScale	Virtex UltraScale+	Zynq UltraScale+
Gen1 (2.5Gb/s)	x8	x16	x8	x16	x16
Gen2 (5Gb/s)	x8	x16	x8	x16	x16
Gen3 (8Gb/s)	x8	x16	x8	x16	x16
Gen4 (16Gb/s) <sup>(1)</sup>		x8		x8	x8

**Notes:**

1. Transceivers in Kintex UltraScale and Virtex UltraScale devices are capable of operating at Gen4 data rates.

For high-performance applications, advanced buffering techniques of the block offer a flexible maximum payload size of up to 1,024 bytes. The integrated block interfaces to the integrated high-speed transceivers for serial connectivity and to block RAMs for data buffering. Combined, these elements implement the Physical Layer, Data Link Layer, and Transaction Layer of the PCI Express protocol.

Xilinx provides a light-weight, configurable, easy-to-use LogiCORE™ IP wrapper that ties the various building blocks (the integrated block for PCIe, the transceivers, block RAM, and clocking resources) into an Endpoint or Root Port solution. The system designer has control over many configurable parameters: link width and speed, maximum payload size, FPGA or MPSoC logic interface speeds, reference clock frequency, and base address register decoding and filtering.

## Stacked Silicon Interconnect (SSI) Technology

Many challenges associated with creating high-capacity devices are addressed by Xilinx with the second generation of the pioneering 3D SSI technology. SSI technology enables multiple super-logic regions (SLRs) to be combined on a passive interposer layer, using proven manufacturing and assembly techniques from industry leaders, to create a single device with more than 20,000 low-power inter-SLR connections. Dedicated interface tiles within the SLRs provide ultra-high bandwidth, low latency connectivity to other SLRs. Table 19 shows the number of SLRs in devices that use SSI technology and their dimensions.

Table 19: UltraScale and UltraScale+ 3D IC SLR Count and Dimensions

	Kintex UltraScale		Virtex UltraScale				Virtex UltraScale+								
Device	KU085	KU115	VU125	VU160	VU190	VU440	VU5P	VU7P	VU9P	VU11P	VU13P	VU31P	VU33P	VU35P	VU37P
# SLRs	2	2	2	3	3	3	2	2	3	3	4	1	1	2	3
SLR Width (in regions)	6	6	6	6	6	9	6	6	6	8	8	8	8	8	8
SLR Height (in regions)	5	5	5	5	5	5	5	5	5	4	4	4	4	4	4

## Clock Management

The clock generation and distribution components in UltraScale devices are located adjacent to the columns that contain the memory interface and input and output circuitry. This tight coupling of clocking and I/O provides low-latency clocking to the I/O for memory interfaces and other I/O protocols. Within every clock management tile (CMT) resides one mixed-mode clock manager (MMCM), two PLLs, clock distribution buffers and routing, and dedicated circuitry for implementing external memory interfaces.

### Mixed-Mode Clock Manager

The mixed-mode clock manager (MMCM) can serve as a frequency synthesizer for a wide range of frequencies and as a jitter filter for incoming clocks. At the center of the MMCM is a voltage-controlled oscillator (VCO), which speeds up and slows down depending on the input voltage it receives from the phase frequency detector (PFD).

There are three sets of programmable frequency dividers (D, M, and O) that are programmable by configuration and during normal operation via the Dynamic Reconfiguration Port (DRP). The pre-divider D reduces the input frequency and feeds one input of the phase/frequency comparator. The feedback divider M acts as a multiplier because it divides the VCO output frequency before feeding the other input of the phase comparator. D and M must be chosen appropriately to keep the VCO within its specified frequency range. The VCO has eight equally-spaced output phases (0°, 45°, 90°, 135°, 180°, 225°, 270°, and 315°). Each phase can be selected to drive one of the output dividers, and each divider is programmable by configuration to divide by any integer from 1 to 128.

The MMCM has three input-jitter filter options: low bandwidth, high bandwidth, or optimized mode. Low-Bandwidth mode has the best jitter attenuation. High-Bandwidth mode has the best phase offset. Optimized mode allows the tools to find the best setting.

The MMCM can have a fractional counter in either the feedback path (acting as a multiplier) or in one output path. Fractional counters allow non-integer increments of 1/8 and can thus increase frequency synthesis capabilities by a factor of 8. The MMCM can also provide fixed or dynamic phase shift in small increments that depend on the VCO frequency. At 1,600MHz, the phase-shift timing increment is 11.2ps.

## PLL

With fewer features than the MMCM, the two PLLs in a clock management tile are primarily present to provide the necessary clocks to the dedicated memory interface circuitry. The circuit at the center of the PLLs is similar to the MMCM, with PFD feeding a VCO and programmable M, D, and O counters. There are two divided outputs to the device fabric per PLL as well as one clock plus one enable signal to the memory interface circuitry.

UltraScale+ MPSoCs are equipped with five additional PLLs in the PS for independently configuring the four primary clock domains with the PS: the APU, the RPU, the DDR controller, and the I/O peripherals.

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## Clock Distribution

Clocks are distributed throughout UltraScale devices via buffers that drive a number of vertical and horizontal tracks. There are 24 horizontal clock routes per clock region and 24 vertical clock routes per clock region with 24 additional vertical clock routes adjacent to the MMCM and PLL. Within a clock region, clock signals are routed to the device logic (CLBs, etc.) via 16 gateable leaf clocks.

Several types of clock buffers are available. The BUFGCE and BUFCE\_LEAF buffers provide clock gating at the global and leaf levels, respectively. BUFGCTRL provides glitchless clock muxing and gating capability. BUFGCE\_DIV has clock gating capability and can divide a clock by 1 to 8. BUFG\_GT performs clock division from 1 to 8 for the transceiver clocks. In MPSoCs, clocks can be transferred from the PS to the PL using dedicated buffers.

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## Memory Interfaces

Memory interface data rates continue to increase, driving the need for dedicated circuitry that enables high performance, reliable interfacing to current and next-generation memory technologies. Every UltraScale device includes dedicated physical interfaces (PHY) blocks located between the CMT and I/O columns that support implementation of high-performance PHY blocks to external memories such as DDR4, DDR3, QDRII+, and RLDRAM3. The PHY blocks in each I/O bank generate the address/control and data bus signaling protocols as well as the precision clock/data alignment required to reliably communicate with a variety of high-performance memory standards. Multiple I/O banks can be used to create wider memory interfaces.

As well as external parallel memory interfaces, UltraScale FPGAs and MPSoCs can communicate to external serial memories, such as Hybrid Memory Cube (HMC), via the high-speed serial transceivers. All transceivers in the UltraScale architecture support the HMC protocol, up to 15Gb/s line rates. UltraScale devices support the highest bandwidth HMC configuration of 64 lanes with a single FPGA.

## Block RAM

Every UltraScale architecture-based device contains a number of 36 Kb block RAMs, each with two completely independent ports that share only the stored data. Each block RAM can be configured as one 36Kb RAM or two independent 18Kb RAMs. Each memory access, read or write, is controlled by the clock. Connections in every block RAM column enable signals to be cascaded between vertically adjacent block RAMs, providing an easy method to create large, fast memory arrays, and FIFOs with greatly reduced power consumption.

All inputs, data, address, clock enables, and write enables are registered. The input address is always clocked (unless address latching is turned off), retaining data until the next operation. An optional output data pipeline register allows higher clock rates at the cost of an extra cycle of latency. During a write operation, the data output can reflect either the previously stored data or the newly written data, or it can remain unchanged. Block RAM sites that remain unused in the user design are automatically powered down to reduce total power consumption. There is an additional pin on every block RAM to control the dynamic power gating feature.

## Programmable Data Width

Each port can be configured as  $32K \times 1$ ;  $16K \times 2$ ;  $8K \times 4$ ;  $4K \times 9$  (or 8);  $2K \times 18$  (or 16);  $1K \times 36$  (or 32); or  $512 \times 72$  (or 64). Whether configured as block RAM or FIFO, the two ports can have different aspect ratios without any constraints. Each block RAM can be divided into two completely independent 18Kb block RAMs that can each be configured to any aspect ratio from  $16K \times 1$  to  $512 \times 36$ . Everything described previously for the full 36Kb block RAM also applies to each of the smaller 18Kb block RAMs. Only in simple dual-port (SDP) mode can data widths of greater than 18bits (18Kb RAM) or 36 bits (36Kb RAM) be accessed. In this mode, one port is dedicated to read operation, the other to write operation. In SDP mode, one side (read or write) can be variable, while the other is fixed to 32/36 or 64/72. Both sides of the dual-port 36Kb RAM can be of variable width.

## Error Detection and Correction

Each 64-bit-wide block RAM can generate, store, and utilize eight additional Hamming code bits and perform single-bit error correction and double-bit error detection (ECC) during the read process. The ECC logic can also be used when writing to or reading from external 64- to 72-bit-wide memories.

## FIFO Controller

Each block RAM can be configured as a 36Kb FIFO or an 18Kb FIFO. The built-in FIFO controller for single-clock (synchronous) or dual-clock (asynchronous or multirate) operation increments the internal addresses and provides four handshaking flags: full, empty, programmable full, and programmable empty. The programmable flags allow the user to specify the FIFO counter values that make these flags go active. The FIFO width and depth are programmable with support for different read port and write port widths on a single FIFO. A dedicated cascade path allows for easy creation of deeper FIFOs.

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## UltraRAM

UltraRAM is a high-density, dual-port, synchronous memory block available in UltraScale+ devices. Both of the ports share the same clock and can address all of the 4K x 72 bits. Each port can independently read from or write to the memory array. UltraRAM supports two types of write enable schemes. The first mode is consistent with the block RAM byte write enable mode. The second mode allows gating the data and parity byte writes separately. UltraRAM blocks can be connected together to create larger memory arrays. Dedicated routing in the UltraRAM column enables the entire column height to be connected together. If additional density is required, all the UltraRAM columns in an SLR can be connected together with a few fabric resources to create single instances of RAM approximately 100Mb in size. This makes UltraRAM an ideal solution for replacing external memories such as SRAM. Cascadable anywhere from 288Kb to 100Mb, UltraRAM provides the flexibility to fulfill many different memory requirements.

## Error Detection and Correction

Each 64-bit-wide UltraRAM can generate, store and utilize eight additional Hamming code bits and perform single-bit error correction and double-bit error detection (ECC) during the read process.

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## High Bandwidth Memory (HBM)

Virtex UltraScale+ HBM devices incorporate 4GB HBM stacks adjacent to the FPGA die. Using stacked silicon interconnect technology, the FPGA communicates to the HBM stacks through memory controllers that connect to dedicated low-inductance interconnect in the silicon interposer. Each Virtex UltraScale+ HBM FPGA contains one or two HBM stacks, resulting in up to 8GB of HBM per FPGA.

The FPGA has 32 HBM AXI interfaces used to communicate with the HBM. Through a built-in switch mechanism, any of the 32 HBM AXI interfaces can access any memory address on either one or both of the HBM stacks due to the flexible addressing feature. This flexible connection between the FPGA and the HBM stacks results in easy floorplanning and timing closure. The memory controllers perform read and write reordering to improve bus efficiency. Data integrity is ensured through error checking and correction (ECC) circuitry.

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## Configurable Logic Block

Every Configurable Logic Block (CLB) in the UltraScale architecture contains 8 LUTs and 16 flip-flops. The LUTs can be configured as either one 6-input LUT with one output, or as two 5-input LUTs with separate outputs but common inputs. Each LUT can optionally be registered in a flip-flop. In addition to the LUTs and flip-flops, the CLB contains arithmetic carry logic and multiplexers to create wider logic functions.

Each CLB contains one slice. There are two types of slices: SLICEL and SLICEM. LUTs in the SLICEM can be configured as 64-bit RAM, as 32-bit shift registers (SRL32), or as two SRL16s. CLBs in the UltraScale architecture have increased routing and connectivity compared to CLBs in previous-generation Xilinx devices. They also have additional control signals to enable superior register packing, resulting in overall higher device utilization.



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## Interconnect

Various length vertical and horizontal routing resources in the UltraScale architecture that span 1, 2, 4, 5, 12, or 16 CLBs ensure that all signals can be transported from source to destination with ease, providing support for the next generation of wide data buses to be routed across even the highest capacity devices while simultaneously improving quality of results and software run time.

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## Digital Signal Processing

DSP applications use many binary multipliers and accumulators, best implemented in dedicated DSP slices. All UltraScale devices have many dedicated, low-power DSP slices, combining high speed with small size while retaining system design flexibility.

Each DSP slice fundamentally consists of a dedicated  $27 \times 18$  bit twos complement multiplier and a 48-bit accumulator. The multiplier can be dynamically bypassed, and two 48-bit inputs can feed a single-instruction-multiple-data (SIMD) arithmetic unit (dual 24-bit add/subtract/accumulate or quad 12-bit add/subtract/accumulate), or a logic unit that can generate any one of ten different logic functions of the two operands.

The DSP includes an additional pre-adder, typically used in symmetrical filters. This pre-adder improves performance in densely packed designs and reduces the DSP slice count by up to 50%. The 96-bit-wide XOR function, programmable to 12, 24, 48, or 96-bit widths, enables performance improvements when implementing forward error correction and cyclic redundancy checking algorithms.

The DSP also includes a 48-bit-wide pattern detector that can be used for convergent or symmetric rounding. The pattern detector is also capable of implementing 96-bit-wide logic functions when used in conjunction with the logic unit.

The DSP slice provides extensive pipelining and extension capabilities that enhance the speed and efficiency of many applications beyond digital signal processing, such as wide dynamic bus shifters, memory address generators, wide bus multiplexers, and memory-mapped I/O register files. The accumulator can also be used as a synchronous up/down counter.

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## System Monitor

The System Monitor blocks in the UltraScale architecture are used to enhance the overall safety, security, and reliability of the system by monitoring the physical environment via on-chip power supply and temperature sensors and external channels to the ADC.

All UltraScale architecture-based devices contain at least one System Monitor. The System Monitor in UltraScale+ FPGAs and the PL of Zynq UltraScale+ MPSoCs is similar to the Kintex UltraScale and Virtex UltraScale devices but with additional features including a PMBus interface.



Zynq UltraScale+ MPSoCs contain an additional System Monitor block in the PS. See [Table 20](#).

**Table 20: Key System Monitor Features**

	Kintex UltraScale Virtex UltraScale	Kintex UltraScale+ Virtex UltraScale+ Zynq UltraScale+ MPSoC PL	Zynq UltraScale+ MPSoC PS
ADC	10-bit 200kSPS	10-bit 200kSPS	10-bit 1MSPS
Interfaces	JTAG, I2C, DRP	JTAG, I2C, DRP, PMBus	APB

In FPGAs and the MPSoC PL, sensor outputs and up to 17 user-allocated external analog inputs are digitized using a 10-bit 200 kilo-sample-per-second (kSPS) ADC, and the measurements are stored in registers that can be accessed via internal FPGA (DRP), JTAG, PMBus, or I2C interfaces. The I2C interface and PMBus allow the on-chip monitoring to be easily accessed by the System Manager/Host before and after device configuration.

The System Monitor in the MPSoC PS uses a 10-bit, 1 mega-sample-per-second (MSPS) ADC to digitize the sensor outputs. The measurements are stored in registers and are accessed via the Advanced Peripheral Bus (APB) interface by the processors and the platform management unit (PMU) in the PS.

## Configuration

The UltraScale architecture-based devices store their customized configuration in SRAM-type internal latches. The configuration storage is volatile and must be reloaded whenever the device is powered up. This storage can also be reloaded at any time. Several methods and data formats for loading configuration are available, determined by the mode pins, with more dedicated configuration datapath pins to simplify the configuration process.

UltraScale architecture-based devices support secure and non-secure boot with optional Advanced Encryption Standard - Galois/Counter Mode (AES-GCM) decryption and authentication logic. If only authentication is required, the UltraScale architecture provides an alternative form of authentication in the form of RSA algorithms. For RSA authentication support in the Kintex UltraScale and Virtex UltraScale families, go to [UG570](#), *UltraScale Architecture Configuration User Guide*.

UltraScale architecture-based devices also have the ability to select between multiple configurations, and support robust field-update methodologies. This is especially useful for updates to a design after the end product has been shipped. Designers can release their product with an early version of the design, thus getting their product to market faster. This feature allows designers to keep their customers current with the most up-to-date design while the product is already deployed in the field.

## Booting MPSoCs

Zynq UltraScale+ MPSoCs use a multi-stage boot process that supports both a non-secure and a secure boot. The PS is the master of the boot and configuration process. For a secure boot, the AES-GCM, SHA-3/384 decryption/authentication, and 4096-bit RSA blocks decrypt and authenticate the image.

Upon reset, the device mode pins are read to determine the primary boot device to be used: NAND, Quad-SPI, SD, eMMC, or JTAG. JTAG can only be used as a non-secure boot source and is intended for debugging purposes. One of the CPUs, Cortex-A53 or Cortex-R5, executes code out of on-chip ROM and copies the first stage boot loader (FSBL) from the boot device to the on-chip memory (OCM).

After copying the FSBL to OCM, the processor executes the FSBL. Xilinx supplies example FSBLs or users can create their own. The FSBL initiates the boot of the PS and can load and configure the PL, or configuration of the PL can be deferred to a later stage. The FSBL typically loads either a user application or an optional second stage boot loader (SSBL) such as U-Boot. Users obtain example SSBL from Xilinx or a third party, or they can create their own SSBL. The SSBL continues the boot process by loading code from any of the primary boot devices or from other sources such as USB, Ethernet, etc. If the FSBL did not configure the PL, the SSBL can do so, or again, the configuration can be deferred to a later stage.

The static memory interface controller (NAND, eMMC, or Quad-SPI) is configured using default settings. To improve device configuration speed, these settings can be modified by information provided in the boot image header. The ROM boot image is not user readable or executable after boot.

## Configuring FPGAs

The SPI (serial NOR) interface (x1, x2, x4, and dual x4 modes) and the BPI (parallel NOR) interface (x8 and x16 modes) are two common methods used for configuring the FPGA. Users can directly connect an SPI or BPI flash to the FPGA, and the FPGA's internal configuration logic reads the bitstream out of the flash and configures itself, eliminating the need for an external controller. The FPGA automatically detects the bus width on the fly, eliminating the need for any external controls or switches. Bus widths supported are x1, x2, x4, and dual x4 for SPI, and x8 and x16 for BPI. The larger bus widths increase configuration speed and reduce the amount of time it takes for the FPGA to start up after power-on.

In master mode, the FPGA can drive the configuration clock from an internally generated clock, or for higher speed configuration, the FPGA can use an external configuration clock source. This allows high-speed configuration with the ease of use characteristic of master mode. Slave modes up to 32 bits wide that are especially useful for processor-driven configuration are also supported by the FPGA. In addition, the new media configuration access port (MCAP) provides a direct connection between the integrated block for PCIe and the configuration logic to simplify configuration over PCIe.

SEU detection and mitigation (SEM) IP, RSA authentication, post-configuration CRC, and Security Monitor (SecMon) IP are not supported in the KU025 FPGA.

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## Packaging

The UltraScale devices are available in a variety of organic flip-chip and lidless flip-chip packages supporting different quantities of I/Os and transceivers. Maximum supported performance can depend on the style of package and its material. Always refer to the specific device data sheet for performance specifications by package type.

In flip-chip packages, the silicon device is attached to the package substrate using a high-performance flip-chip process. Decoupling capacitors are mounted on the package substrate to optimize signal integrity under simultaneous switching of outputs (SSO) conditions.

# Ordering Information

Table 21 shows the speed and temperature grades available in the different device families.  $V_{CCINT}$  supply voltage is listed in parentheses.

Table 21: Speed Grade and Temperature Grade

Device Family	Devices	Speed Grade and Temperature Grade			
		Commercial (C)	Extended (E)		Industrial (I)
		0°C to +85°C	0°C to +100°C	0°C to +110°C	–40°C to +100°C
Kintex UltraScale	All		-3E <sup>(1)</sup> (1.0V)		
			-2E (0.95V)		-2I (0.95V)
		-1C (0.95V)			-1I (0.95V)
					-1LI <sup>(1)</sup> (0.95V or 0.90V)
Kintex UltraScale+	All		-3E (0.90V)		
			-2E (0.85V)		-2I (0.85V)
				-2LE <sup>(2)</sup> (0.85V or 0.72V)	
			-1E (0.85V)		-1I (0.85V)
					-1LI (0.85V or 0.72V)
Virtex UltraScale	VU065 VU080 VU095 VU125 VU160 VU190		-3E (1.0V)		
			-2E (0.95V)		-2I (0.95V)
			-1HE (0.95V or 1.0V)		-1I (0.95V)
	VU440		-3E (1.0V)		
			-2E (0.95V)		-2I (0.95V)
		-1C (0.95V)			-1I (0.95V)
Virtex UltraScale+	VU3P VU5P VU7P VU9P VU11P VU13P		-3E (0.90V)		
			-2E (0.85V)		-2I (0.85V)
				-2LE <sup>(2)</sup> (0.85V or 0.72V)	
			-1E (0.85V)		-1I (0.85V)
	VU31P VU33P VU35P VU37P		-3E (0.90V)		
			-2E (0.85V)		
				-2LE <sup>(2)</sup> (0.85V or 0.72V)	
			-1E (0.85V)		

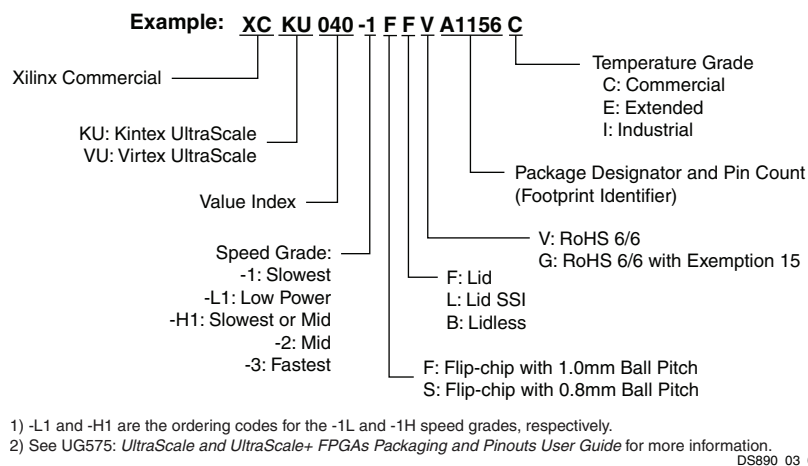
Table 21: Speed Grade and Temperature Grade (Cont'd)

Device Family	Devices	Speed Grade and Temperature Grade			
		Commercial (C)	Extended (E)		Industrial (I)
		0°C to +85°C	0°C to +100°C	0°C to +110°C	–40°C to +100°C
Zynq UltraScale+	CG Devices		-2E (0.85V)		-2I (0.85V)
				-2LE <sup>(2)(3)</sup> (0.85V or 0.72V)	
			-1E (0.85V)		-1I (0.85V)
					-1LI <sup>(3)</sup> (0.85V or 0.72V)
	ZU2EG ZU3EG		-2E (0.85V)		-2I (0.85V)
				-2LE <sup>(2)(3)</sup> (0.85V or 0.72V)	
			-1E (0.85V)		-1I (0.85V)
					-1LI <sup>(3)</sup> (0.85V or 0.72V)
	ZU4EG ZU5EG ZU6EG ZU7EG ZU9EG ZU11EG ZU15EG ZU17EG ZU19EG		-3E (0.90V)		
			-2E (0.85V)		-2I (0.85V)
				-2LE <sup>(2)(3)</sup> (0.85V or 0.72V)	
			-1E (0.85V)		-1I (0.85V)
					-1LI <sup>(3)</sup> (0.85V or 0.72V)
			-3E (0.90V)		
			-2E (0.85V)		-2I (0.85V)
				-2LE <sup>(2)(3)</sup> (0.85V or 0.72V)	
			-1E (0.85V)		-1I (0.85V)
					-1LI <sup>(3)</sup> (0.85V or 0.72V)
	EV Devices		-3E (0.90V)		
			-2E (0.85V)		-2I (0.85V)
				-2LE <sup>(2)(3)</sup> (0.85V or 0.72V)	
			-1E (0.85V)		-1I (0.85V)
					-1LI <sup>(3)</sup> (0.85V or 0.72V)

**Notes:**

- KU025 and KU095 are not available in -3E or -1LI speed/temperature grades.
- In -2LE speed/temperature grade, devices can operate for a limited time with junction temperature of 110°C. Timing parameters adhere to the same speed file at 110°C as they do below 110°C, regardless of operating voltage (nominal at 0.85V or low voltage at 0.72V). Operation at 110°C Tj is limited to 1% of the device lifetime and can occur sequentially or at regular intervals as long as the total time does not exceed 1% of device lifetime.
- In Zynq UltraScale+ MPSoCs, when operating the PL at low voltage (0.72V), the PS operates at nominal voltage (0.85V).

The ordering information shown in [Figure 3](#) applies to all packages in the Kintex UltraScale and Virtex UltraScale FPGAs. Refer to the Package Marking section of [UG575, UltraScale and UltraScale+ FPGAs Packaging and Pinouts User Guide](#) for a more detailed explanation of the device markings.



**Figure 3: Kintex UltraScale and Virtex UltraScale FPGA Ordering Information**